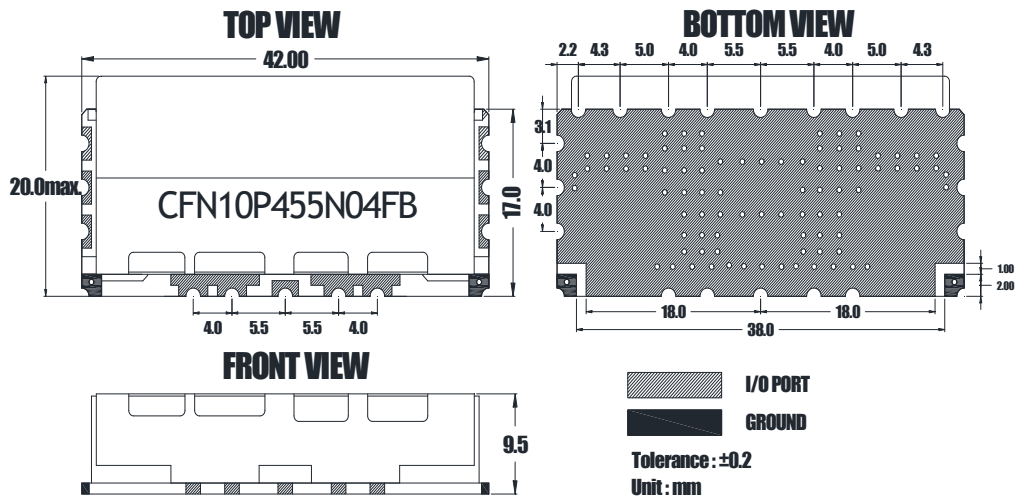


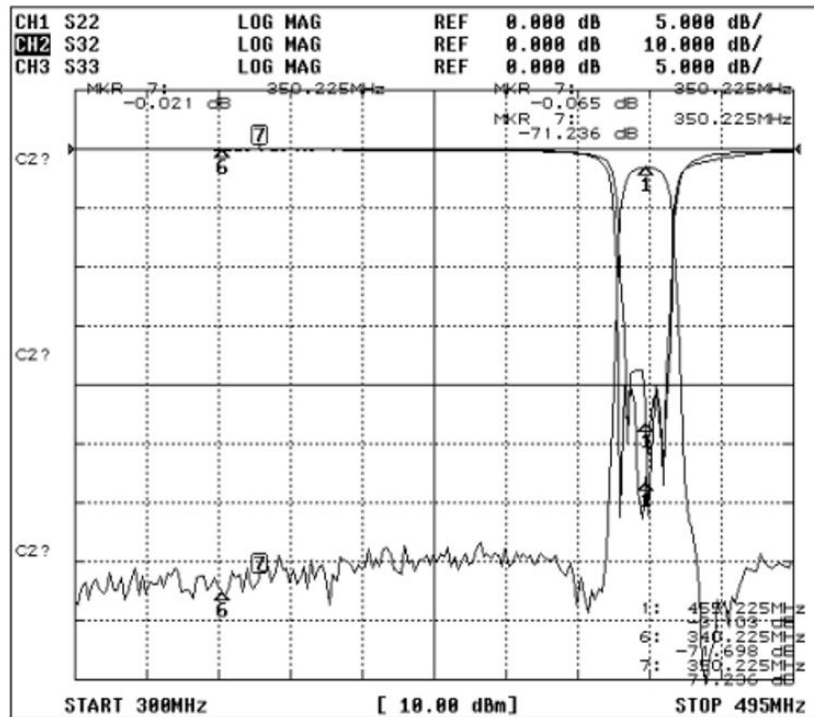
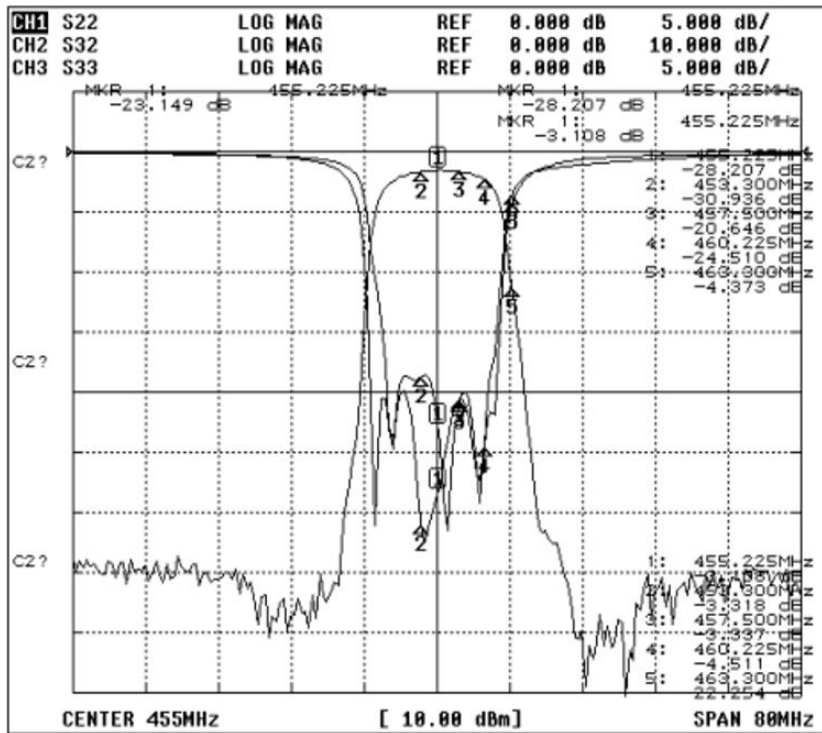
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	455.250	MHz
Bandwidth [BW]	fo ±2.250 [453.000 ~ 457.500]	MHz
Insertion Loss in BW	3.5	dB max
Ripple in BW	0.8 TYP: 0.5	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	4.0 dB min. @ fo + 5.0 [ & 460.225 ]	MHz
	20.0 dB min. @ fo + 8.075 [ & 463.300 ]	MHz
	40.0 dB min. @ fo - 115.0 [340.225 & ]	MHz
	35.0 dB min. @ fo - 105.0 [350.225 & ]	MHz
Group Delay Variation		ns max
Input Power	1.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

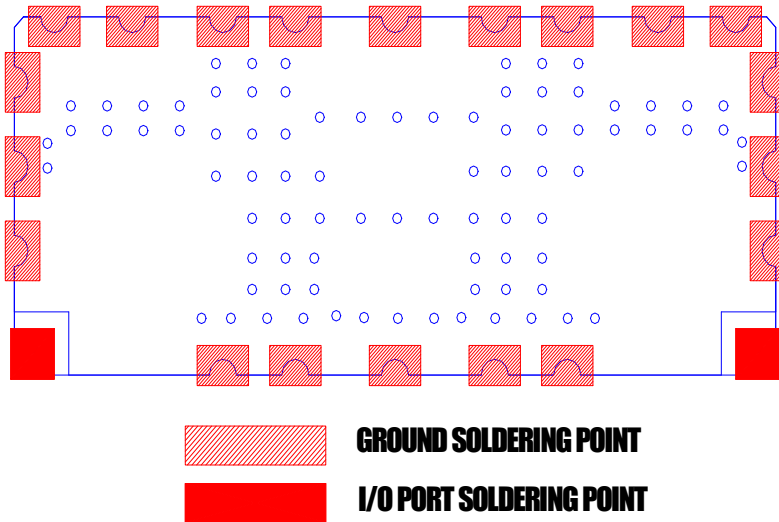
Mechanical Specification



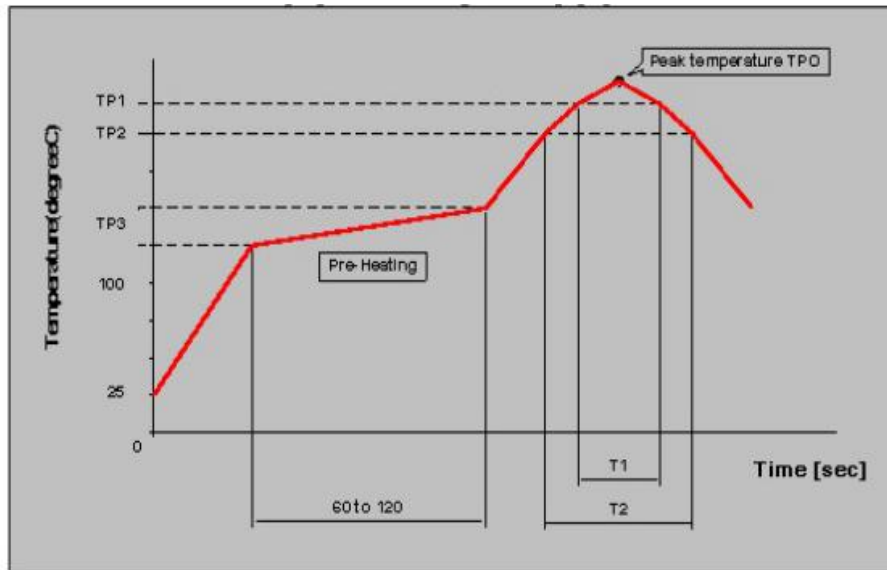
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device  
 Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245 $\pm$ 5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260 $\pm$ 5/0	240	20	220	70	150 to 180